

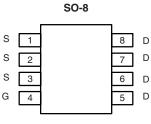
RoHS

COMPLIANT

Vishay Siliconix

## N-Channel 80-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
80	0.013 at V <sub>GS</sub> = 10 V	17.3	35 nC		



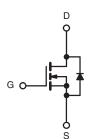
Top View

#### FEATURES

- Halogen-free
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

#### **APPLICATIONS**

- Primary Side Switch
- Half Bridge
- Intermediate Bus Converter



N-Channel MOSFET

Ordering Information: Si4110DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	80	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		17.3		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I_	13.9		
Continuous Brain Gurrent (1) = 150 °C)	T <sub>A</sub> = 25 °C		11.7 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		9.4 <sup>b, c</sup>	Α	
Pulsed Drain Current		I <sub>DM</sub>	60	A	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		6.5		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	IS	3 <sup>b, c</sup>		
Single Pulse Avalanche Current L = 0.1 mH		I <sub>AS</sub>	35		
Single Pulse Avalanche Energy		E <sub>AS</sub>	61.3	mJ	
	T <sub>C</sub> = 25 °C		7.8		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	5	w	
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C		3.6 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C		2.3 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature)			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical Maximum		Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	29	35	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	13	16		

Notes:

a. Based on  $T_C = 25 \ ^{\circ}C$ .

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 80 °C/W.



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<b>SPECIFICATIONS</b> $T_J = 25 \ ^{\circ}C$ , Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static	-,						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	80			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			84		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 9.8			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2		4	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 80 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	1 10 μΑ	
		$V_{DS} = 80 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10$ V, $V_{GS} = 10$ V	20			А	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.7 A		0.0108	0.0130	Ω	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 11.7 A		23		S	
Dynamic <sup>b</sup>	<u> </u>			1	<u> </u>		
Input Capacitance	C <sub>iss</sub>			2205		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, f = 1 MHz		260			
Reverse Transfer Capacitance	C <sub>rss</sub>			78			
Total Gate Charge	Q <sub>g</sub>			35	53		
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.7 A		12.5		nC	
Gate-Drain Charge	Q <sub>gd</sub>			8			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.22	1.1	2.2	Ω	
Turn-on Delay Time	t <sub>d(on)</sub>			18	27	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 40 V, $R_{I}$ = 4.3 $\Omega$		10	18		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 9.4 \text{ A}, V_{GEN} = 8 \text{ V}, R_g = 1 \Omega$		22	33		
Fall Time	t <sub>f</sub>	-		8	16		
Turn-On Delay Time	t <sub>d(on)</sub>			15	23		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 40 V, $R_L$ = 4.3 $\Omega$		9	18		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 9.4 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		22	33		
Fall Time	t <sub>f</sub>			7	14		
Drain-Source Body Diode Characteristi	cs		1				
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			6.5	^	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				60	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 9.4 A		0.80	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			45	68	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 0.4  A d/dt = 100  A/us  T = 05  °C		82	123	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 9.4 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$		34			
Reverse Recovery Rise Time	t <sub>b</sub>	$\neg$		11		ns	

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %

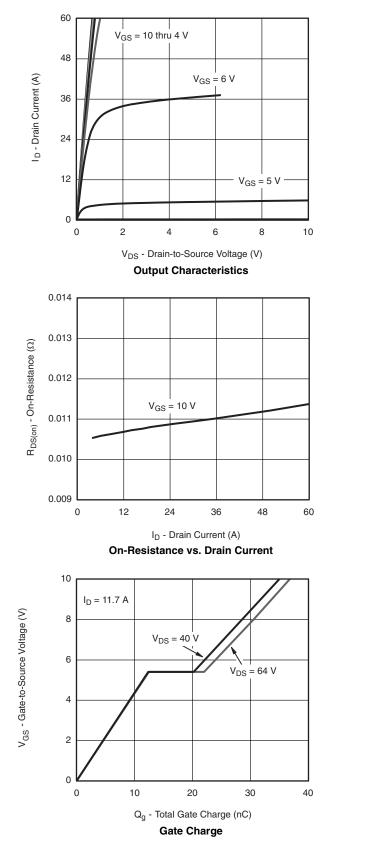
b. Guaranteed by design, not subject to production testing.

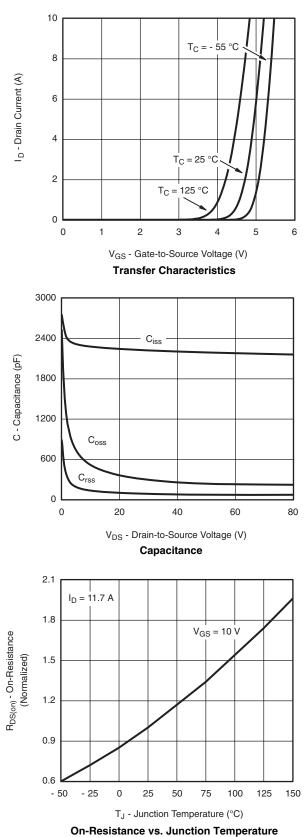
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

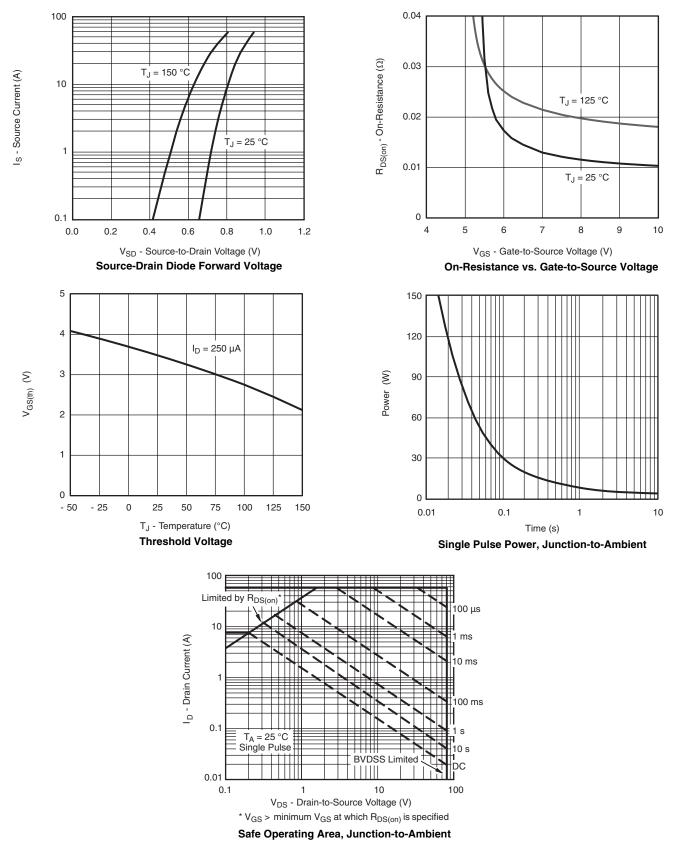




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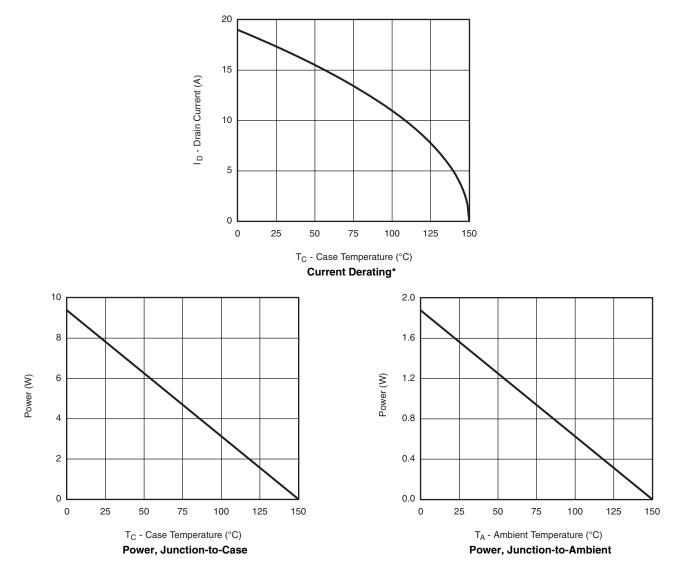
#### **TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted





## Si4110DY Vishay Siliconix

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

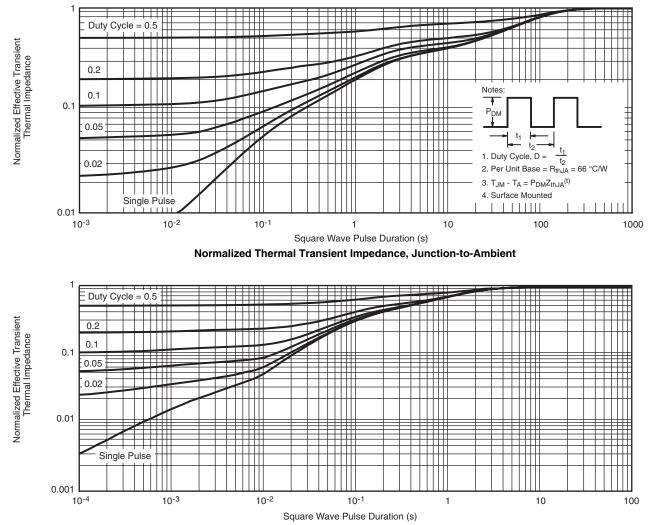


\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?68766.



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